

REMARKS

The objections set forth to the claims have been cured.

Claim 11 was rejected under Section 102 based on Akamatsu. Among other things, claim 11 calls for a pair of heat generating integrated circuit chips with a cooling integrated circuit chip between them. There is no cooling integrated circuit chip in Akamatsu. In Akamatsu, the cooling is done by a cold plate 5. The cold plate is not a cooling integrated circuit and it is not between a pair of heat generating integrated circuit chips. It simply contacts each of a plurality of chips but is not positioned between them. As shown in Figure 2, for example, there is nothing between any of the adjacent integrated circuits 2. A gap is provided there.

Therefore, reconsideration of the rejection of claim 11 is respectfully requested.

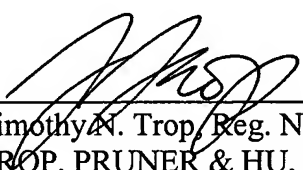
Claim 22 was also rejected based on Akamatsu. Claim 22 calls for a stack including a pair of integrated circuit chips and a cooling integrated circuit chip between the pair of integrated circuit chips. Clearly, there is no stack which includes three integrated circuit chips with the cooling integrated circuit chip between the pair of integrated circuit chips.

References in the rejection to chips 2 that are the two outer chips are not understood. In each chip 2 there is only one chip. The element 6, which is over the chip, is actually a compound. See column 4, line 28. The element 3 is a heat conductor. The element 1 is a printed circuit board. Thus, there is no pair of stacked chips.

In view of these remarks, reconsideration is respectfully requested.

Respectfully submitted,

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